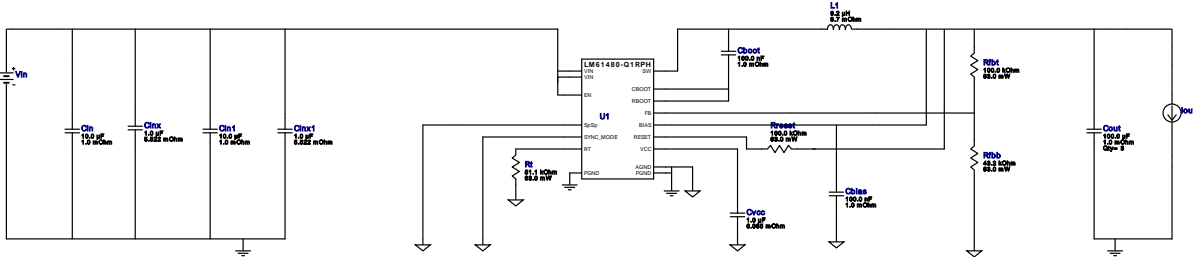


WEBENCH® Design Report

Design : 53 LM61480QRPHRQ1
LM61480QRPHRQ1 5V-7.4V to 3.30V @ 1.75A



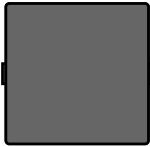

Design Alerts

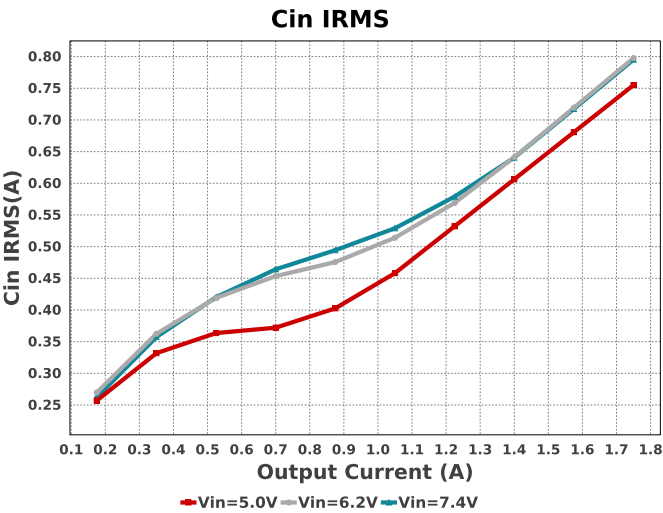
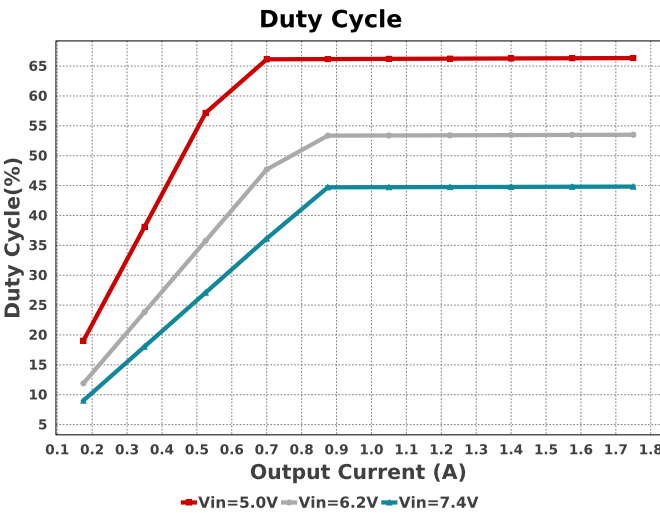
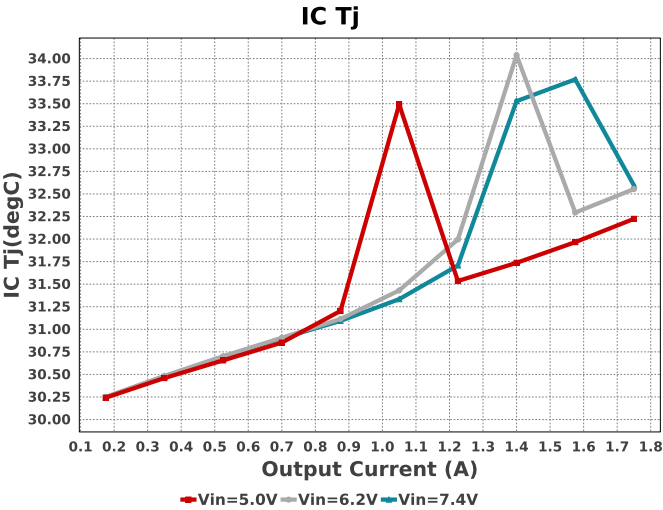
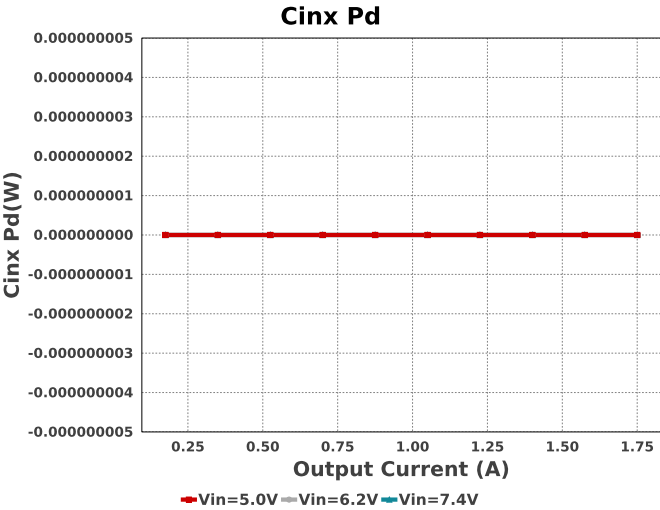
Component Selection Information

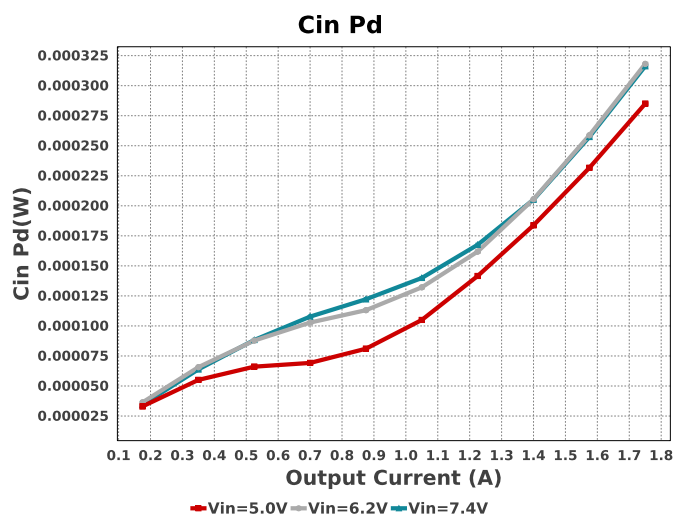
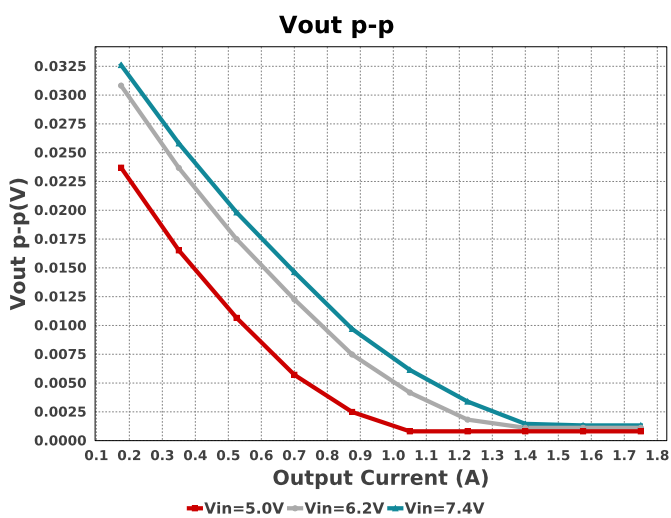
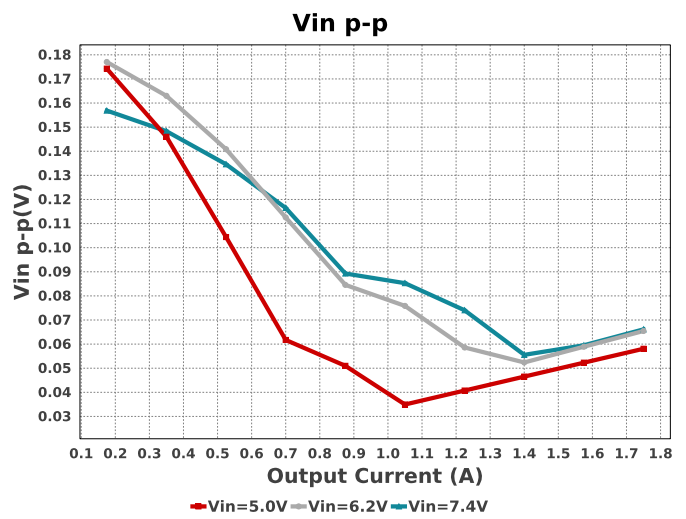
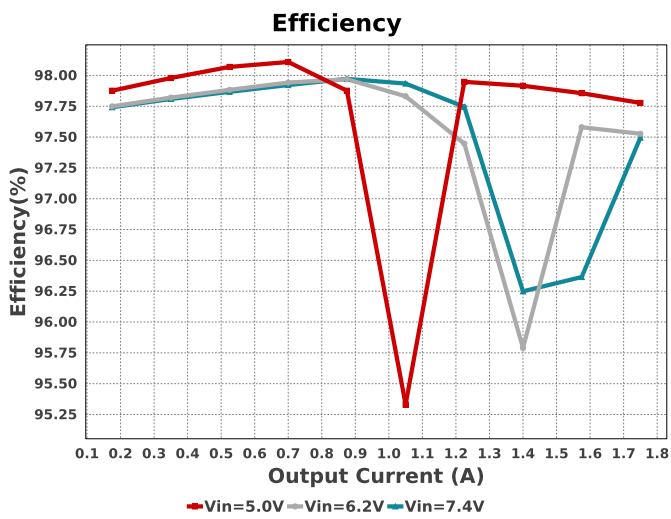
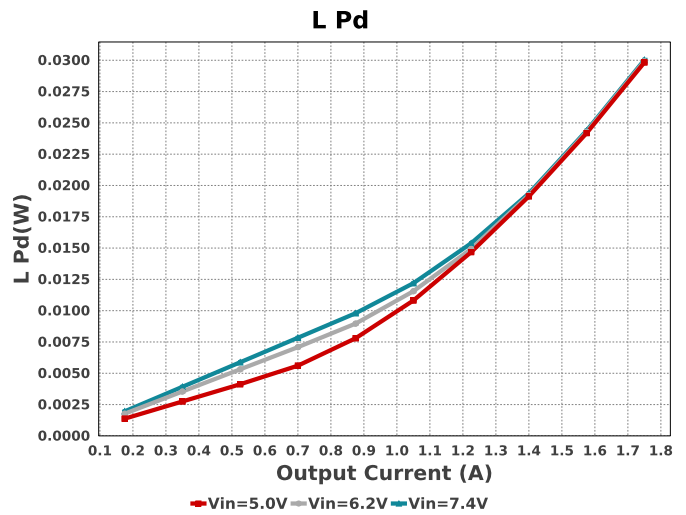
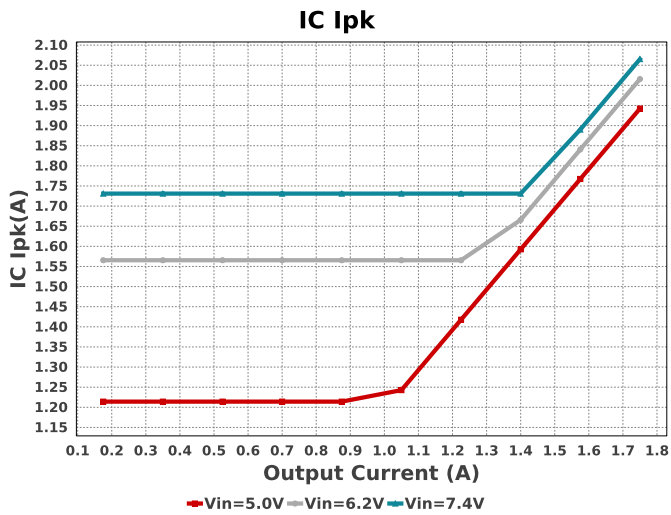
The LM61480-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application. This device can work in steady state at Vin = 3V. However, needs a minimum of 3.6V during start up. See datasheet for details.

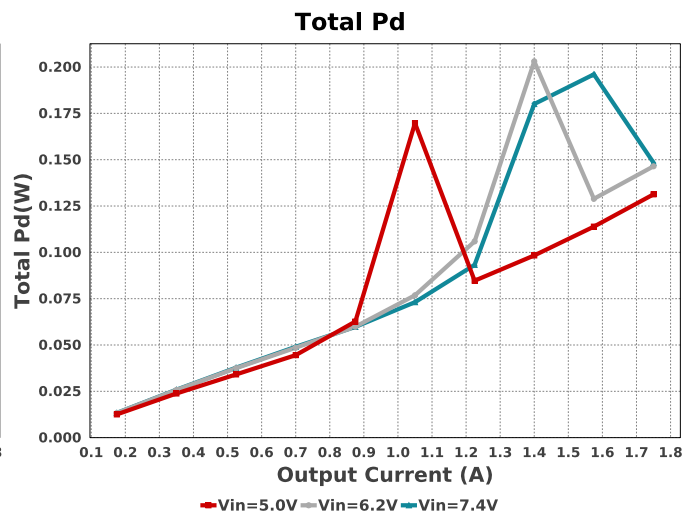
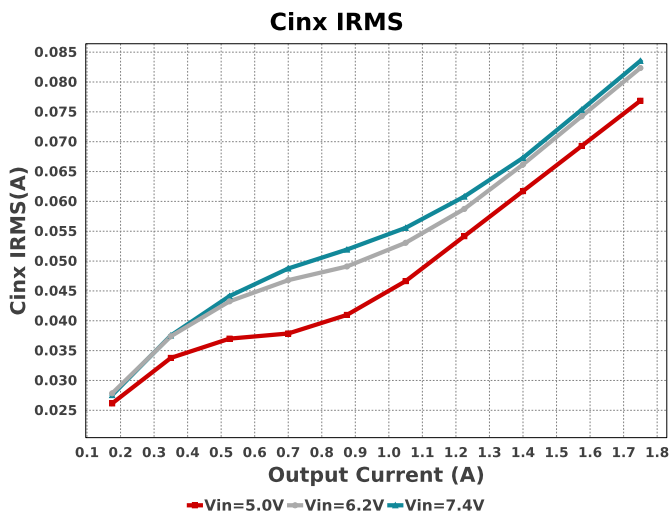
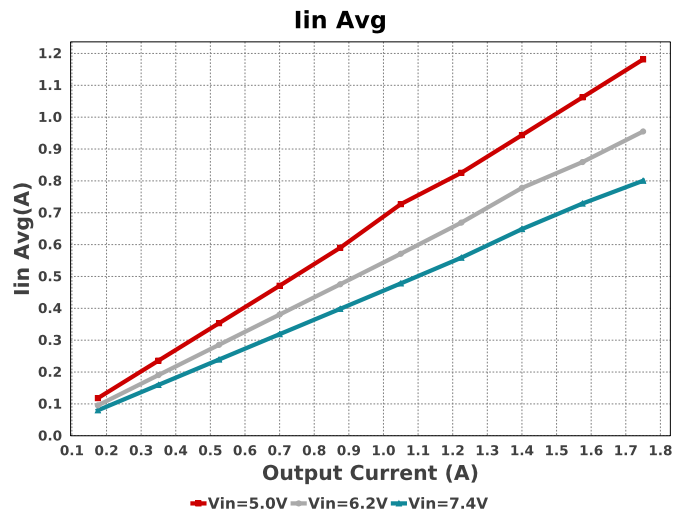
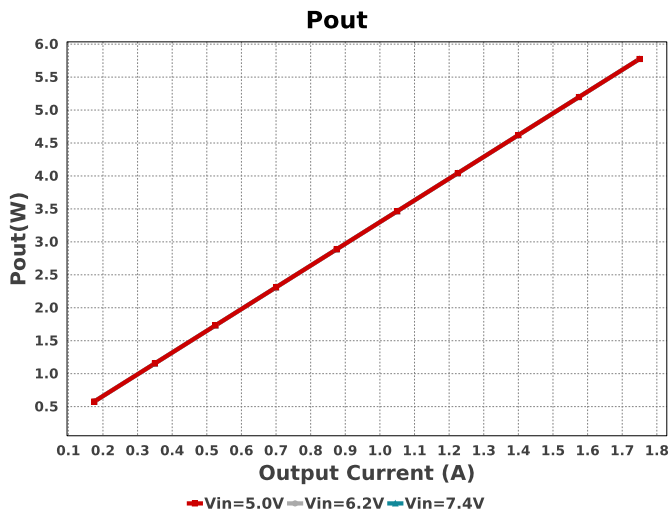
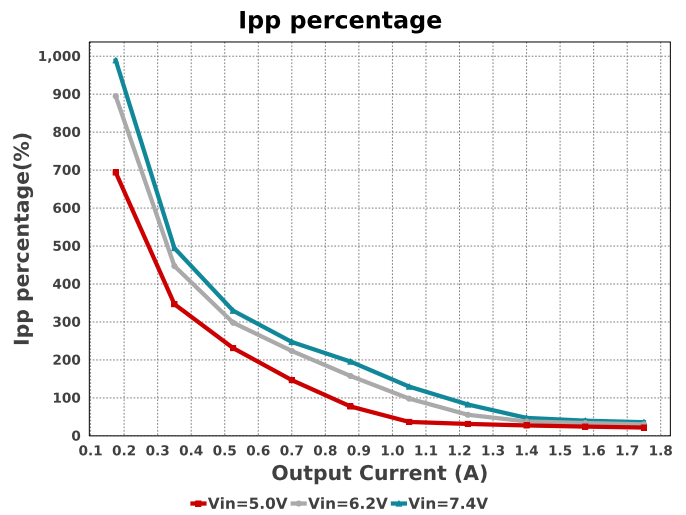
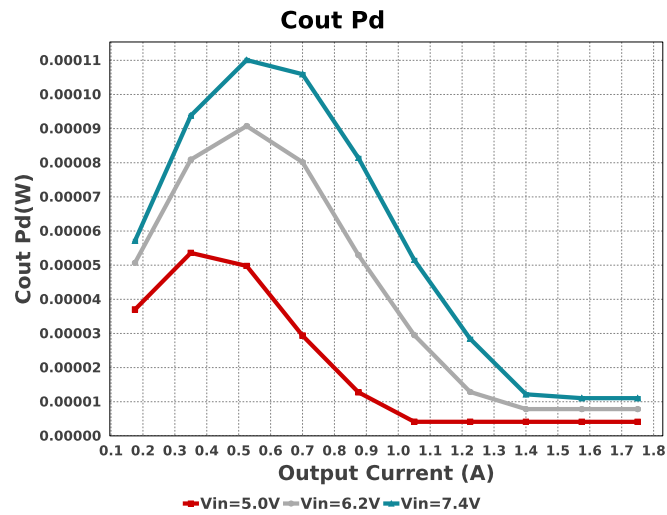
Electrical BOM

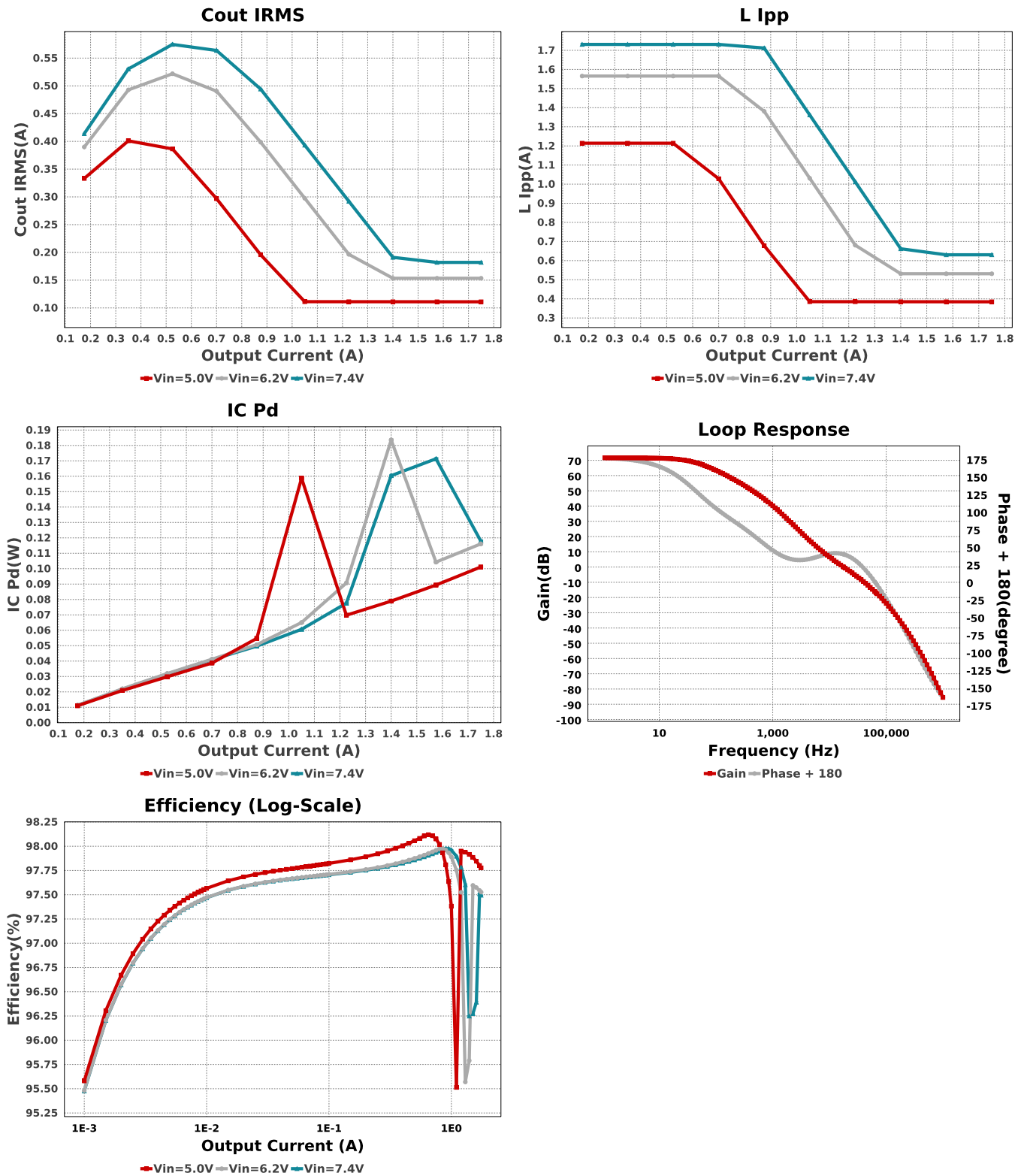
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cbias	MuRata	GRM155R71C104KA88D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cboot	MuRata	GRM155R71A104KA01D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 10.0 V IRMS= 0.0 A	1	\$0.01	0402 3 mm ²
Cin	MuRata	GRM32ER71H106KA12L Series= X7R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 6.0 A	1	\$0.47	1210_270 15 mm ²
Cin1	MuRata	GRM32ER71H106KA12L Series= X7R	Cap= 10.0 uF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 6.0 A	1	\$0.47	1210_270 15 mm ²
Cinx	TDK	C1608X5R1H105K080AB Series= X5R	Cap= 1.0 uF ESR= 5.522 mOhm VDC= 50.0 V IRMS= 2.2162 A	1	\$0.03	0603 5 mm ²
Cinx1	TDK	C1608X5R1H105K080AB Series= X5R	Cap= 1.0 uF ESR= 5.522 mOhm VDC= 50.0 V IRMS= 2.2162 A	1	\$0.03	0603 5 mm ²
Cout	MuRata	GRM32EC80J107ME20L Series= X6S	Cap= 100.0 uF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 6.0 A	3	\$0.17	1210_270 15 mm ²
Cvcc	MuRata	GRM188R60J105KA01D Series= X5R	Cap= 1.0 uF ESR= 6.065 mOhm VDC= 6.3 V IRMS= 1.36934 A	1	\$0.01	0603 5 mm ²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
L1	Coilcraft	MLC1565-922MLB	L= 9.2 µH 9.7 mOhm	1	\$1.05	 MLC1565 243 mm²
Rfbb	Vishay-Dale	CRCW040243K2FKED Series= CRCW..e3	Res= 43.2 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm²
Rfbt	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm²
Rreset	Vishay-Dale	CRCW0402100KFKED Series= CRCW..e3	Res= 100.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm²
Rt	Vishay-Dale	CRCW040251K1FKED Series= CRCW..e3	Res= 51.1 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm²
U1	Texas Instruments	LM61480QRPHRQ1	Switcher	1	\$2.14	RPH0016A 25 mm²









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	795.265 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	316.22 μ W	Capacitor	Input capacitor power dissipation
3.	Cinx IRMS	83.54 mA	Capacitor	Bulk capacitor RMS ripple current
4.	Cinx Pd	0.0 W	Capacitor	Bulk capacitor power dissipation
5.	Cout IRMS	182.016 mA	Capacitor	Output capacitor RMS ripple current
6.	Cout Pd	11.043 μ W	Capacitor	Output capacitor power dissipation
7.	IC Ipk	2.065 A	IC	Peak switch current in IC
8.	IC Pd	117.95 mW	IC	IC power dissipation
9.	IC Tj	32.595 degC	IC	IC junction temperature
10.	ICThetaJA Effective	22.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
11.	Iin Avg	800.46 mA	IC	Average input current

#	Name	Value	Category	Description
12.	Ipp percentage	36.03 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
13.	L Ipp	630.52 mA	Inductor	Peak-to-peak inductor ripple current
14.	L Pd	30.028 mW	Inductor	Inductor power dissipation
15.	Cin Pd	316.22 μ W	Power	Input capacitor power dissipation
16.	Cinx Pd	0.0 W	Power	Bulk capacitor power dissipation
17.	Cout Pd	11.043 μ W	Power	Output capacitor power dissipation
18.	IC Pd	117.95 mW	Power	IC power dissipation
19.	L Pd	30.028 mW	Power	Inductor power dissipation
20.	Total Pd	148.381 mW	Power	Total Power Dissipation
21.	BOM Count	16	System	Total Design BOM count
			Information	
22.	Cross Freq	17.854 kHz	System	Bode plot crossover frequency
			Information	
23.	Duty Cycle	44.832 %	System	Duty cycle
			Information	
24.	Efficiency	97.495 %	System	Steady state efficiency
			Information	
25.	FootPrint	373.0 mm ²	System	Total Foot Print Area of BOM components
			Information	
26.	Frequency	315.559 kHz	System	Switching frequency
			Information	
27.	Gain Marg	-16.818 dB	System	Bode Plot Gain Margin
			Information	
28.	Iout	1.75 A	System	Iout operating point
			Information	
29.	Low Freq Gain	71.61 dB	System	Gain at 1Hz
			Information	
30.	Mode	CCM	System	Conduction Mode
			Information	
31.	Phase Marg	41.219 deg	System	Bode Plot Phase Margin
			Information	
32.	Pout	5.775 W	System	Total output power
			Information	
33.	Total BOM	\$4.77	System	Total BOM Cost
			Information	
34.	Vin	7.4 V	System	Vin operating point
			Information	
35.	Vin p-p	66.116 mV	System	Peak-to-peak input voltage
			Information	
36.	Vout	3.3 V	System	Operational Output Voltage
			Information	
37.	Vout Actual	3.315 V	System	Vout Actual calculated based on selected voltage divider resistors
			Information	
38.	Vout Tolerance	2.425 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
			Information	
39.	Vout p-p	1.322 mV	System	Peak-to-peak output ripple voltage
			Information	

Design Inputs

Name	Value	Description
Iout	1.75	Maximum Output Current
VinMax	7.4	Maximum input voltage
VinMin	5.0	Minimum input voltage
VinTyp	6.6	Typical input voltage
Vout	3.3	Output Voltage
base_pn	LM61480-Q1	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature
UserFsw	309.0 k	Customer Selected Frequency

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of $L1$ before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

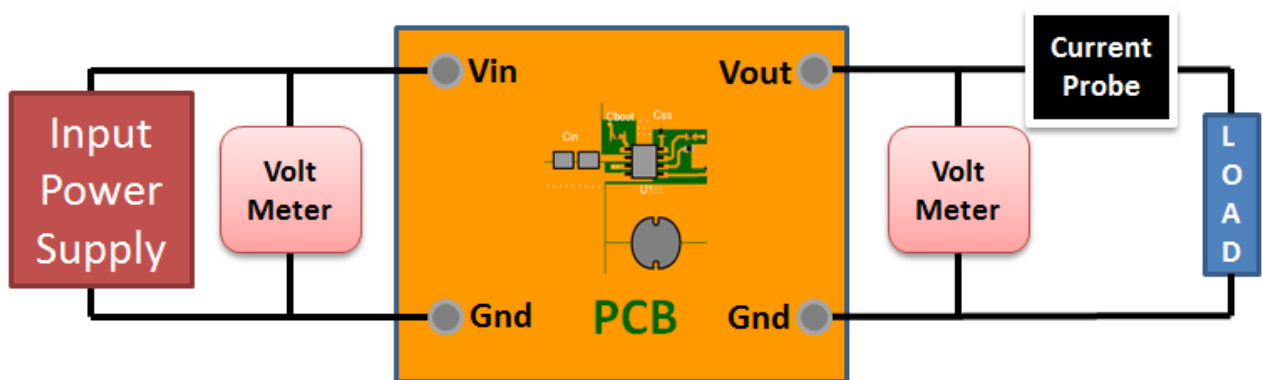
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 5.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. The LM61480-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. This device can work in steady state at $V_{in} = 3V$. However, needs a minimum of 3.6V during start up. See datasheet for details The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application
2. Master key : 27AFC3A06A218B6F8EA41ED3B4C0DDB7[v1]
3. **LM61480-Q1** Product Folder : <http://www.ti.com/product/LM61480%2DQ1> : contains the data sheet and other resources.

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